

September 30, 2021

To whom it may concern,

Company name: SUMCO Corporation

Representative: Mayuki Hashimoto, Representative Director

CEO & Chairman of the Board (Code: 3436, TSE First Section)

Contact: Hiroshi Shibuya, Executive Officer

General Manager of Public Relations & IR Department

(Tel: +81-3-5444-3915)

Announcement Regarding Capital Investments (Acquisition of Fixed Assets)

SUMCO Corporation (the "Company" and together with its group companies, the "Company Group") hereby announces that it has resolved, at the meeting of the board of directors held today, to implement the following capital investments.

1. Purpose of the Capital Investments

Demand for 300 mm silicon wafers continues to grow steadily, and the supply of 300 mm leadingedge silicon wafers that the Company can provide with the Company Group's current manufacturing facilities is not able to keep up with demand.

In order to fulfill its supply responsibilities in the 300 mm leading-edge silicon wafer market, the Company has continued to increase its production capacity in stages in line with the growth of the market demand. However, since the Company Group's existing plants in Japan are currently running out of space for capacity expansions, the Company has decided to implement capital investments for a new plant building, utility equipment and manufacturing equipment in order to enable itself to continue to increase its production capacity for 300 mm leading-edge silicon wafers in stages. The Company has also decided that SUMCO TECHXIV Corp., a subsidiary of the Company, will make a capital investment related to a physical expansion of an existing plant, utility equipment and manufacturing equipment.

For more details on the issuance of new shares through a public offering as set forth below, please refer to the "Announcement Regarding Issuance of New Shares" dated September 30, 2021.

2. Details of the Capital Investments

for manufacturing of 300 mm leading-edge silicon wafers

b) Location Imari, Saga Prefecture (the Company)

Omura, Nagasaki Prefecture (SUMCO TECHXIV Corp.)

c) Planned investment amount The Company

A plant building and utility equipment 78.6 billion yen Wafer manufacturing equipment 122.9 billion yen

Note: This press release does not constitute an offer or sale of securities in the United States. The shares of common stock of the Company (the "securities") have not been and will not be registered under the U.S. Securities Act of 1933 (the "Securities Act"). The securities may not be offered or sold in the United States absent registration or an exemption from registration under the Securities Act. With respect to the issuance of new shares, the securities will not be registered in the United States.

Total 201.5 billion yen

SUMCO TECHXIV Corp.

A plant building and utility equipment
Wafer manufacturing equipment
Total

16.5 billion yen
10.7 billion yen
27.2 billion yen

d) Method of funding Issuance of new shares through a public offering and the

Company's own funds

e) Schedule The Company and SUMCO TECHXIV Corp. plan to begin the

construction of the plant buildings and installation of utility equipment in 2022, and to begin production in stages from 2023 after the introduction of manufacturing equipment. The capital investment to be made by SUMCO TECHXIV Corp. is scheduled to be completed within 2023, and the capital investment to be

made by the Company within 2024.

3. Future Outlook

There will be no impact of this capital investment on the Company Group's performance results for this fiscal year.

End

Note: This press release does not constitute an offer or sale of securities in the United States. The shares of common stock of the Company (the "securities") have not been and will not be registered under the U.S. Securities Act of 1933 (the "Securities Act"). The securities may not be offered or sold in the United States absent registration or an exemption from registration under the Securities Act. With respect to the issuance of new shares, the securities will not be registered in the United States.